

A

B

C

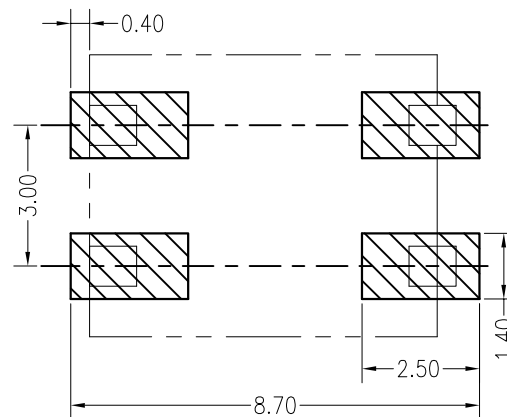
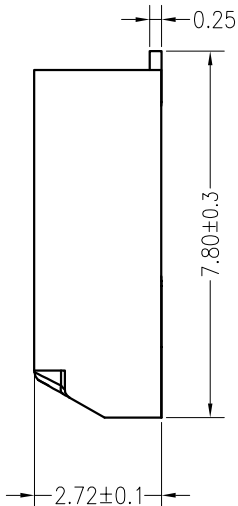
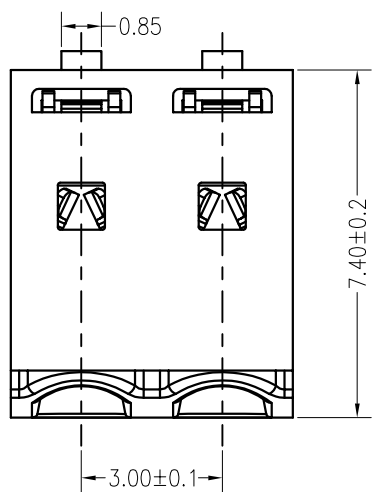
D

E

F

REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	吴丹平	2017.08.31

1

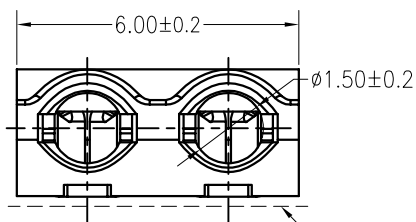


Board Layout

主要技术参数 Main Specifications

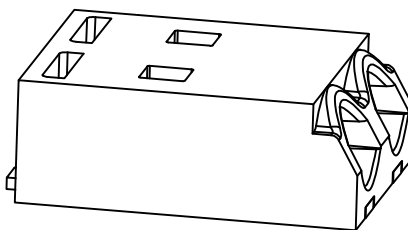
线数 (Poles): 01 to 03
 接触电阻 (Contact resistance): $\leq 20\text{m}\Omega$
 绝缘电阻 (Insulation resistance): $\geq 800\text{M}\Omega$
 额定电压 (Rated voltage): 275V AC DC
 额定电流 (Rated current): 2.0A AC DC
 耐电压 (Withstand Voltage): 800V AC/minute
 温度范围 (Temperature Range): $-40^{\circ}\text{C} \sim +110^{\circ}\text{C}$

3

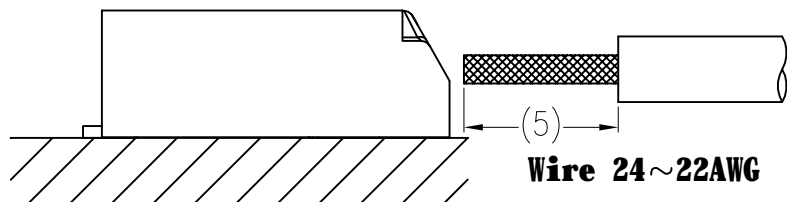


0.15 Max

4



5



Wire 24~22AWG



ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
B	CONTACT	2 PCS	PhosphorBronze	Matte Sn
A	HOUSING	2 PCS	LCP/PA9T	UL 94V-0, COLOR:BEIGE

LEDsconn			TITLE: -	
X.±0.5	X.±5'	USE: CUSTOMER	3.0mmPITCH 90°WAFER SMT TYPE	
.X±0.3	.X±2'		PART NO.:	
.XX±0.25	.XX±1'	APPD: 邵敬和	DWG NO.:	
--	--	CHKD: 田峰	SCALE	
⊕	⊖	UNITS: mm	DR: 吴丹平	SHEET
				1 : 1
				1 / 1

A

B

C

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